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(54) Title: ULTRA HIGH VOID VOLUME POLISHING PAD WITH CLOSED PORE STRUCTURE

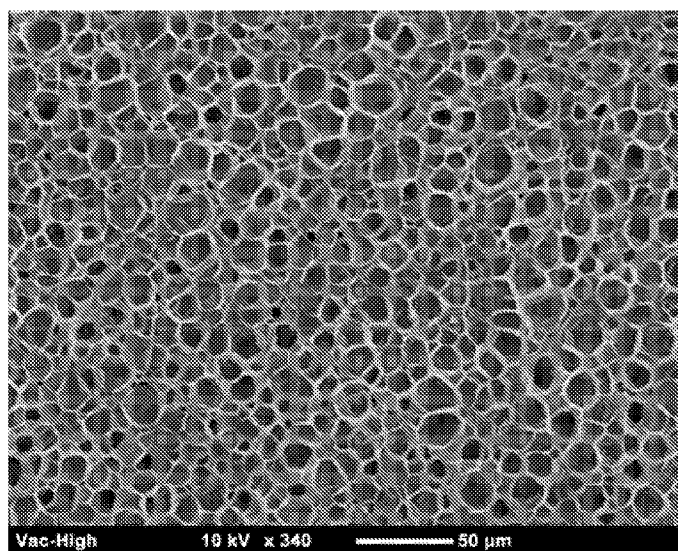


FIG. 1C

(57) Abstract: The invention provides a polishing pad for chemical mechanical polishing comprising a porous polymeric material, wherein the polishing pad comprises closed pores and wherein the polishing pad has a void volume fraction of 70% or more. Also disclosed is a method for preparing the aforesaid polishing pad and a method of polishing a substrate by use of the aforesaid polishing pad.



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